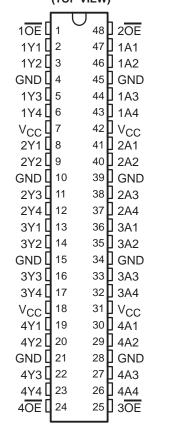
SCLS327G - MARCH 1996 - REVISED JANUARY 2000

- Members of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V_{CC}
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'AHC16244 devices are 16-bit buffers and line drivers designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

SN54AHC16244 . . . WD PACKAGE SN74AHC16244 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. They provide true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHC16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHC16244 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 4-bit buffer/driver)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z



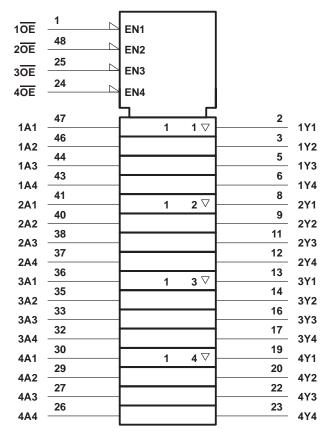
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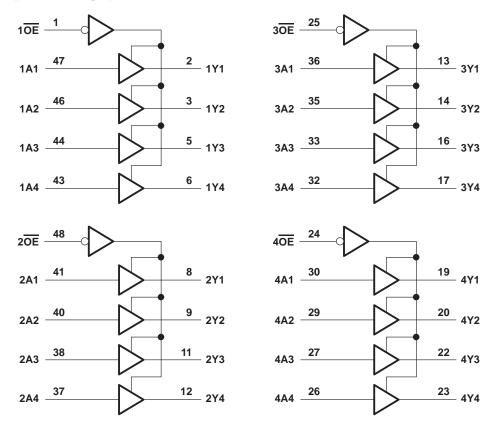
logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

	DGG package DGV package	-0.5 V to 7 V -0.5 V to V _{CC} + 0.5 V -20 mA ±20 mA ±25 mA ±75 mA 70°C/W 58°C/W
	DL package	63°C/W
Storago tomporataro rango, istg		00 0 10 100 0

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



SN54AHC16244, SN74AHC16244 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

			SN54AH0	C16244	SN74AH0	16244	LINUT	
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
VIH	High-level input voltage	VCC = 3 V	2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85			
		V _{CC} = 2 V		0.5		0.5		
VIL	Low-level input voltage	VCC = 3 V		0.9		0.9	V	
		V _{CC} = 5.5 V		1.65 1.65				
٧ı	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0.4	Vcc	0	VCC	V	
		V _{CC} = 2 V	(C)	- 50		-50	μΑ	
IOH	High-level output current	$V_{CC} = 3.3 \pm 0.3 \text{ V}$	Ž	-4		-4	mA	
		$V_{CC} = 5 \pm 0.5 \text{ V}$	Q.	-8		-8		
		V _{CC} = 2 V		50		50	μΑ	
loL	Low-level output current	$V_{CC} = 3.3 \pm 0.3 \text{ V}$		4		4	mA	
		$V_{CC} = 5 \pm 0.5 \text{ V}$		8		8	IIIA	
Δt/Δν	langet transition rise or fall rate	V _{CC} = 3.3 ± 0.3 V		100		100	20/1	
ΔυΔν	Input transition rise or fall rate	$V_{CC} = 5 \pm 0.5 \text{ V}$		20		20	ns/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T/	λ = 25°C	;	SN54AHC	16244	SN74AHC16244		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		1.9		
	I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9		
Voн		4.5 V	4.4	4.5		4.4		4.4		V
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8	4	3.8		
		2 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1	4	0.1		0.1	
VOL		4.5 V			0.1	2/2	0.1		0.1	V
	I _{OL} = 4 mA	3 V			0.36	0/2	0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36	20	0.5		0.44	
lį	V _I = V _{CC} or GND	0 V to 5.5 V			±0.1	40	±1*		±1	μΑ
loz	$V_O = V_{CC}$ or GND, $V_I (\overline{OE}) = V_{IL}$ or V_{IH}	5.5 V			±0.25		±2.5		±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μΑ
C _i	$V_I = V_{CC}$ or GND	5 V		2	10				10	pF
Co	$V_O = V_{CC}$ or GND	5 V		3.5						pF

 $^{^{*}}$ On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.



switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	λ = 25°C	;	SN54AH0	C16244	SN74AH0	16244	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
t _{PLH}	А	Y	C _I = 15 pF		5.8*	8.4*	1*	10*	1	10	ns
t _{PHL}	ζ.	'	C[= 15 μ·		5.8*	8.4*	1*	10*	1	10	115
^t PZH	ŌĒ	Y	C _I = 15 pF		6.6*	10.6*	1*	12.5*	1	12.5	ns
tPZL	OE	'	CL = 15 μι		6.6*	10.6*	1*	12.5*	1	12.5	115
^t PHZ	ŌĒ	Y	C _I = 15 pF		5*	11.5*	1*	12.5*	1	12.5	ns
tPLZ	OE	'	CL = 15 μι		5*	11.5*	1* 4	12.5*	1	12.5	115
^t PLH	А	Y	C ₁ = 50 pF		8.3	11.9	1	13.5	1	13.5	ns
t _{PHL}	ζ	'	CL = 30 βi		8.3	11.9	$\gamma_{ m G}$	13.5	1	13.5	110
^t PZH	ŌĒ	Y	C 50 pE		9.1	14.1	O 1	16	1	16	ns
tPZL	OE	'	Y $C_L = 50 \text{ pF}$		9.1	14.1	1	16	1	16	115
^t PHZ	ŌĒ	Y	C _I = 50 pF		10.3	14	1	16	1	16	ns
tPLZ	UE T		1 CL = 50 pr		10.3	14	1	16	1	16	115
tsk(o)			C _L = 50 pF			1.5**				1.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	FROM TO LOAD		TA	= 25°C	;	SN54AH	C16244	SN74AHC	16244	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
t _{PLH}	А	Υ	C _I = 15 pF		3.9*	6*	1*	7*	1	6.5	ns
t _{PHL}	ζ	'	CL = 13 pr		3.9*	6*	1*	7*	1	6.5	115
^t PZH	ŌĒ	Y	C _L = 15 pF		4.7*	7.3*	1*	8.5*	1	8.5	ns
t _{PZL}	OE	'	GL = 13 pr		4.7*	7.3*	1*	8.5*	1	8.5	115
^t PHZ	ŌĒ	Y	C _I = 15 pF		5*	7.2*	1*	8.5*	1	8.5	ns
t _{PLZ}	OE	'	CL = 13 pr		5*	7.2*	1* 2	8.5*	1	8.5	115
tPLH	А	Y	C ₁ = 50 pF		5.4	8	1	9	1	8.5	ns
t _{PHL}	ζ	'	OL = 30 pr		5.4	8	770	9	1	8.5	115
^t PZH	ŌĒ	Υ	C _I = 50 pF		6.2	9.3	^O 1	10.5	1	10.5	ns
tPZL	OE	'	CL = 30 pr		6.2	9.3	1	10.5	1	10.5	115
^t PHZ	ŌĒ	Υ	C _I = 50 pF		6.7	9.2	1	10.5	1	10.5	ne
t _{PLZ}	OE	ľ	GL = 50 pr		6.7	9.2	1	10.5	1	10.5	ns
tsk(o)			C _L = 50 pF			1**				1	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.

^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.

SN54AHC16244, SN74AHC16244 **16-BIT BUFFERS/DRIVERS** WITH 3-STATE OUTPUTS SCLS327G - MARCH 1996 - REVISED JANUARY 2000

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN74	UNIT		
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5		V
V _{OL} (V)	Quiet output, minimum dynamic V _{OL}		-0.2		V
VOH(V)	Quiet output, minimum dynamic VOH		4.8		V
VIH(D)	High-level dynamic input voltage	3.5			V
V _{IL(D)}	Low-level dynamic input voltage			1.5	V

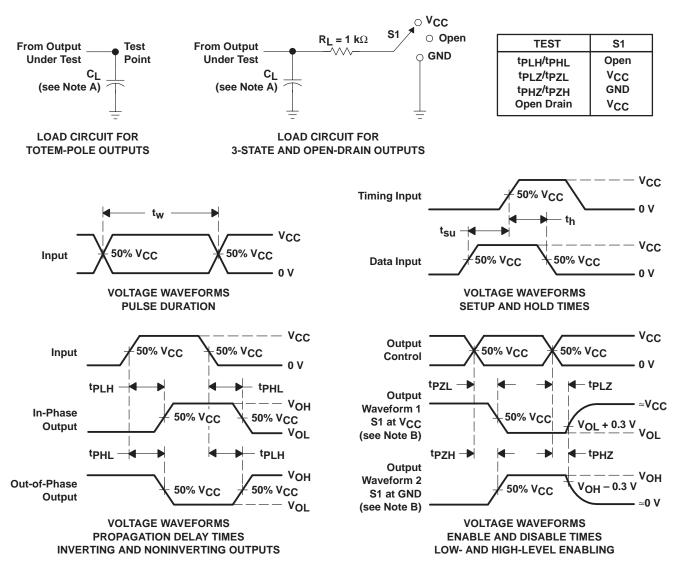
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	10.5	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AHC16244DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16244DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16244DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16244DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16244DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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